

Introduction

- Expected problems ...
- Disadvantages ...
- Wishes ...

WT production needs

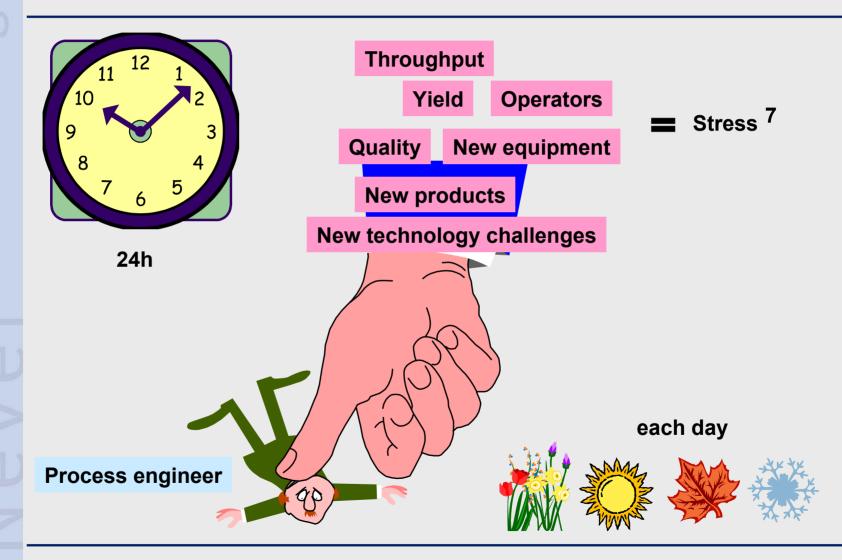
- Incoming inspection ...
- Scrub-analysis ...
- Identifying prober / probe card problems ...

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Conclusion

A new kind of inspection microscope is the answer







Working on the leading egde of probing technology



Introduction of advanced PC-technologies in a short time frame



Changes

- * smaler tip dimensions
- * new tip forms
- * new contact materials
- * lower contact force
- * a lot more contact tips
- * different PC-technologies
- * different cleaning materials



Problems

- * position stability, penetration depth
- * lifetime
- * robustness
- * burned tips
- * needle search
- * more observation efforts
- * cleaning optimization



Light Microscope

- * working distance
- * limited resolution
- * only 2D



SEM

- * located in PFA
- * long operation time
- * limited chamber size



Probe Mark Analyzer

- * no production PMI-System
- * additional system
- * utilization low



expensiv, takes long, a lot more floor space, damage risc, ...

How can you control the wafer probing process?



Laser Scan Microscope

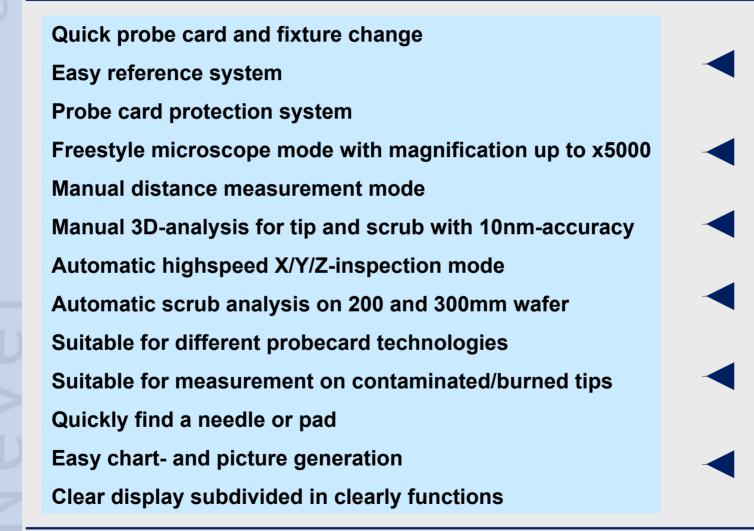
- * not specialized for wafer probing,
- * no PC fixture
- * no PC protection system



Probe Card Analyzer

- * damage risc
- * measurement problems
- * correlations
- * upgrades





production problems Quick registration of



Microscope Mode

manual

Image capture

Distance measurement

3D-Analysis

Reference

Inspection Mode

semi automatic

Free style

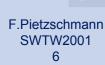
Search a Pin

Scan mode

<u>automatic</u>

Autoinspection XYZ

Autoinspection 3D

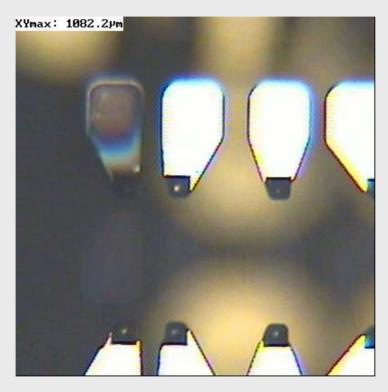




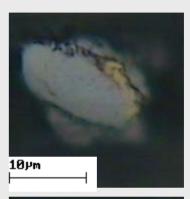
Higher probe card precision reduces the flow

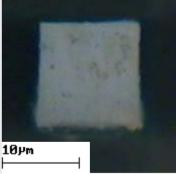
Checks	Contents	
(1) Manufacturer Data	- Outcoming inspection (PCA-Data: X,Y,Z, tip-dia., Caps, Leakage)	
	- Inspection sheet (Spec)	
10 min	- Drawings*) components, wiring *) only for the 1st card	
	- Vendor Audit**) (outcoming process control) **) once per year	
(2) Optical Inspection	- visual (components, soldering, cleanness)	
	- Inspection microscope (tip quality of 1% of the needles)	
10 min		
(3) Tester Correlation	- Prober Setup (1st/last contact, PCB-Bending, Scrubs)	
	- Wafer correlation (yield difference < limit)	
~ 2h***)	***) depends on the test time	





smallest magnification





highest magnification

Automatic file name generation:

design x DUT_PCno_pin_date_time

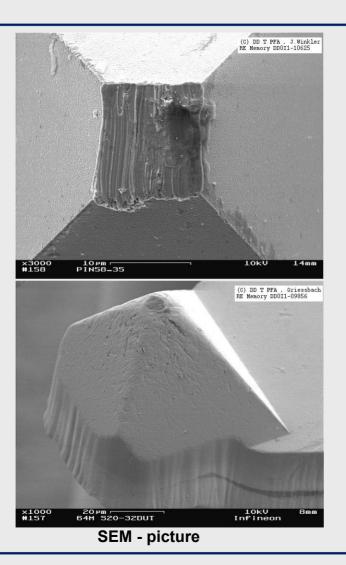
picture size 400x400 pixel

128MSGRAMx16_15_01052_09/04/2001_09:24

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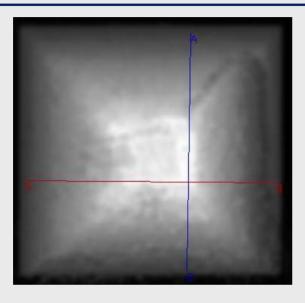
Taking a microscope picture with magnification up to the needle tip











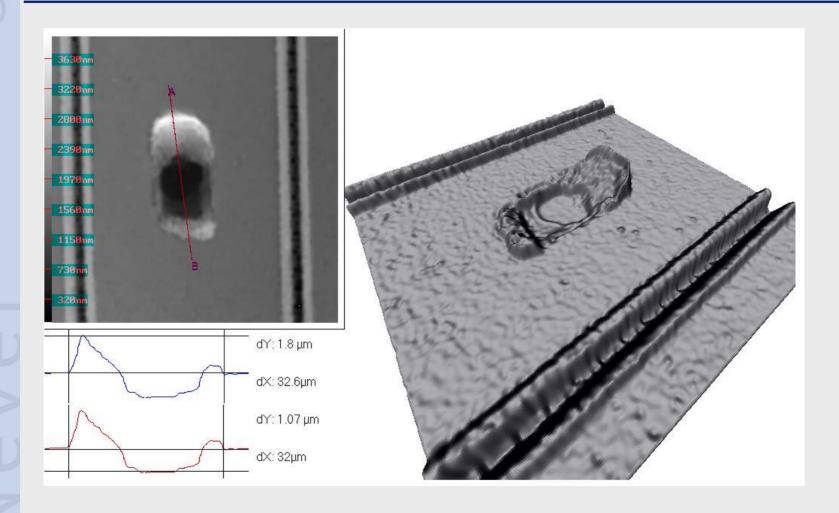
2D picture



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3D image









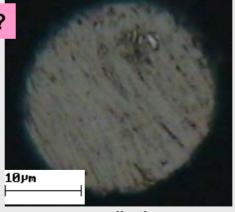


after 750 cleaning TD's

How many cleaning TD's ?

What is the best cleaning material?

How good is the tip refreshment process ?

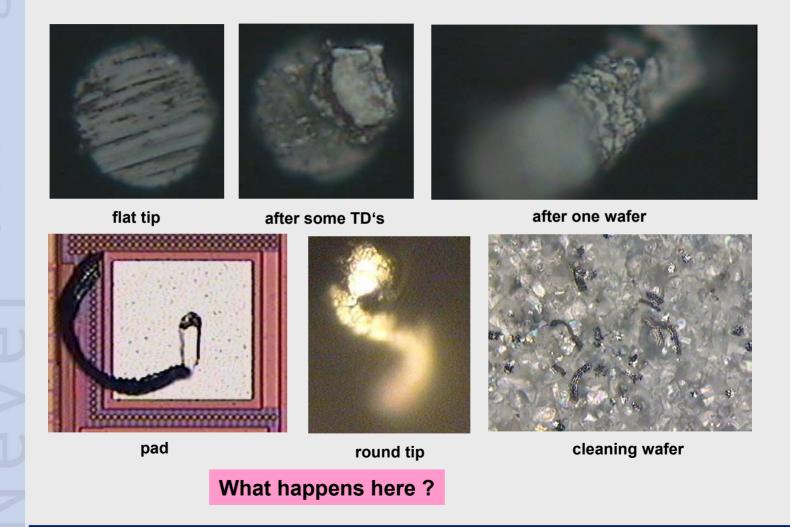


new needle tip

10 µм

after tip refreshment process









How to find a needle tip in an array of 20.000?

The inspection microscope should do this automatically by one click on the pad name, pad map or pad function

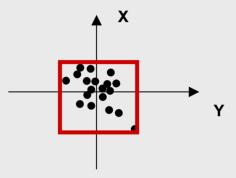




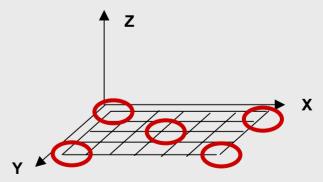
Highspeed measurement: 50 pins/min

Is this card in spec?

Points of interest

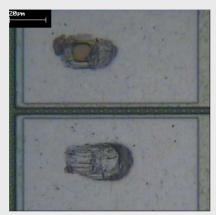


X/Y-Pos-Err min. and max.



1st/last contact, edge and center of the array





What is the difference / reason?

Bonding requirements

no exposed oxyde

scrub size

max, number of touchdowns

TV-opening [μm] pad area [μm²] max. probemark area [μm²] 100x100 10.000 2500 72x72 5184 1296 25% 65x65 4225 1056

Designer requirements

min. padsize min. pitch

thinner aluminum

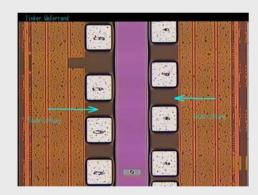
active structures under the pad

How do we get statistical data about the WT production limits?



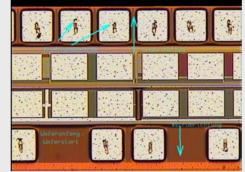
Problem

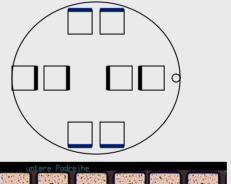
unequal srub length on wafer edge

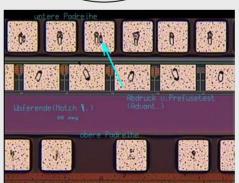


Reason

- chuck tilting
- chuck movement







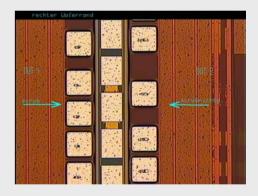
Facts

Probe card: Cantilever 2DUT

Temperature: RT

Chuck type: standard Z stage

Force: about 3kg



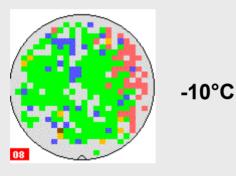
Solution

change to a high rigid Z stage



Problem

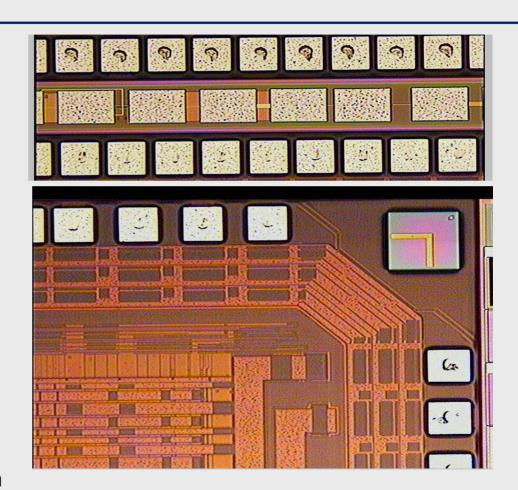
unequal scrub marks in one needle row after 3/4 of the wafer



red chips = VF-OPN

Reason

temperature depends on needle movement



Solution

decrease in tip diameter => increase in penetration depth





SYNCOTEC

CCD camera

probe card fixture

wafer fixture

joystick

computer



TV-monitor

computer monitor

microscope bridge

X/Y-stage

keyboard

You will learn a lot more about your probecards and your probing process



different requirements on a probe card analyzer

Using Epoxy-PC-Technology



Lithographic-PC-Technology

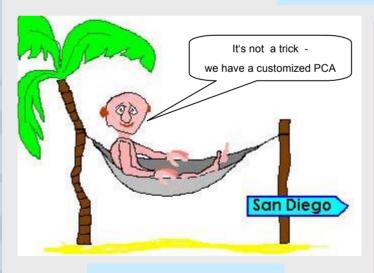
Using as

PC-Manufacturer



PC-User

customized probe card analyzer for the WT floor



Process engineer

- * universal
- * compact
- * high speed measurement
- * data reduction
- * fast problem finding
- * 3D-option is a must
- * protection for PC damages

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You will save time, money and floor space